

PRELIMINARY AMENDMENT
New U.S. Application for PCT/JP99/05003

A1 Conductor 1
19. An electroless plating process which comprises immersing a substrate in the electroless plating solution according to Claim 14 and performing electroless copper plating at a deposition rate set to 1 to 2 $\mu\text{m}/\text{hour}$.

A2
21. A process for manufacturing a printed circuit board which comprises immersing a resin insulating substrate board in the electroless plating solution according to Claim 14 and performing electroless copper plating at a deposition rate set to 1 to 2 $\mu\text{m}/\text{hour}$ to provide a conductor circuit.

A3
44. The multilayer printed circuit board according to Claim 40 wherein said lower-layer via holes are filled with metal.

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